

# J309, J310

Preferred Device

## JFET VHF/UHF Amplifiers

### N-Channel — Depletion

#### Features

- Pb-Free Packages are Available\*

#### MAXIMUM RATINGS

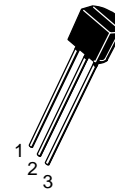
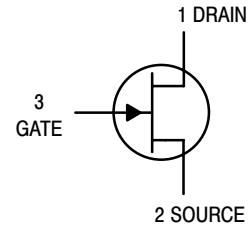
Rating	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	25	Vdc
Gate-Source Voltage	$V_{GS}$	25	Vdc
Forward Gate Current	$I_{GF}$	10	mAdc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above = $25^\circ\text{C}$	$P_D$	350 2.8	mW mW/ $^\circ\text{C}$
Junction Temperature Range	$T_J$	-65 to +125	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-65 to +150	$^\circ\text{C}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



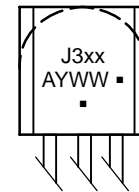
ON Semiconductor®

<http://onsemi.com>



TO-92  
CASE 29-11  
STYLE 5

#### MARKING DIAGRAM



J3xx = Device Code  
 xx = 09 or 10  
 A = Assembly Location  
 Y = Year  
 WW = Work Week  
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# J309, J310

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Gate–Source Breakdown Voltage (I <sub>G</sub> = –1.0 μAdc, V <sub>DS</sub> = 0)	V <sub>(BR)GSS</sub>	–25	–	–	Vdc
Gate Reverse Current (V <sub>GS</sub> = –15 Vdc, V <sub>DS</sub> = 0, T <sub>A</sub> = 25°C) (V <sub>GS</sub> = –15 Vdc, V <sub>DS</sub> = 0, T <sub>A</sub> = +125°C)	I <sub>GSS</sub>	–	–	–1.0 –1.0	nAdc μAdc
Gate Source Cutoff Voltage (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 1.0 nAdc)	V <sub>GS(off)</sub>	–1.0 –2.0	–	–4.0 –6.5	Vdc
<b>ON CHARACTERISTICS</b>					
Zero–Gate–Voltage Drain Current <sup>(1)</sup> (V <sub>DS</sub> = 10 Vdc, V <sub>GS</sub> = 0)	I <sub>DSS</sub>	12 24	–	30 60	mAdc
Gate–Source Forward Voltage (V <sub>DS</sub> = 0, I <sub>G</sub> = 1.0 mAdc)	V <sub>GS(f)</sub>	–	–	1.0	Vdc
<b>SMALL–SIGNAL CHARACTERISTICS</b>					
Common–Source Input Conductance (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 10 mAdc, f = 100 MHz)	Re(y <sub>is</sub> )	–	0.7 0.5	–	mmhos
Common–Source Output Conductance (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 10 mAdc, f = 100 MHz)	Re(y <sub>os</sub> )	–	0.25	–	mmhos
Common–Gate Power Gain (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 10 mAdc, f = 100 MHz)	G <sub>pg</sub>	–	16	–	dB
Common–Source Forward Transconductance (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 10 mAdc, f = 100 MHz)	Re(y <sub>fs</sub> )	–	12	–	mmhos
Common–Gate Input Conductance (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 10 mAdc, f = 100 MHz)	Re(y <sub>ig</sub> )	–	12	–	mmhos
Common–Source Forward Transconductance (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 10 mAdc, f = 1.0 kHz)	g <sub>fs</sub>	10000 8000	–	20000 18000	μmhos
Common–Source Output Conductance (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 10 mAdc, f = 1.0 kHz)	g <sub>os</sub>	–	–	250	μmhos
Common–Gate Forward Transconductance (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 10 mAdc, f = 1.0 kHz)	g <sub>fg</sub>	–	13000 12000	–	μmhos
Common–Gate Output Conductance (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 10 mAdc, f = 1.0 kHz)	g <sub>og</sub>	–	100 150	–	μmhos
Gate–Drain Capacitance (V <sub>DS</sub> = 0, V <sub>GS</sub> = –10 Vdc, f = 1.0 MHz)	C <sub>gd</sub>	–	1.8	2.5	pF
Gate–Source Capacitance (V <sub>DS</sub> = 0, V <sub>GS</sub> = –10 Vdc, f = 1.0 MHz)	C <sub>gs</sub>	–	4.3	5.0	pF
<b>FUNCTIONAL CHARACTERISTICS</b>					
Equivalent Short–Circuit Input Noise Voltage (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 10 mAdc, f = 100 Hz)	$\bar{e}_n$	–	10	–	nV/√Hz

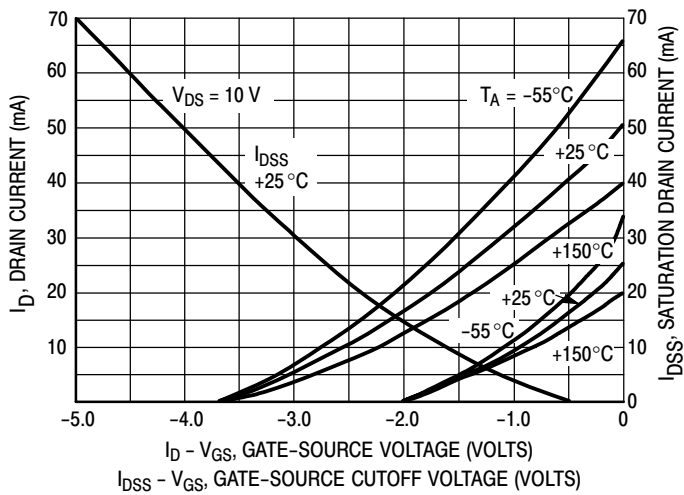
1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 3.0%.

# J309, J310

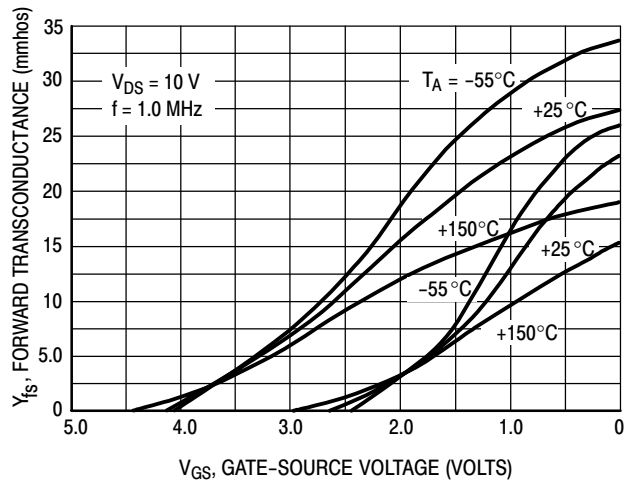
## ORDERING INFORMATION

Device	Package	Shipping†
J309	TO-92	1000 Units / Bulk
J309G	TO-92 (Pb-Free)	
J310	TO-92	1000 Units / Bulk
J310G	TO-92 (Pb-Free)	
J310RLRP	TO-92	2000 Units / Tape & Ammo Box
J310RLRPG	TO-92 (Pb-Free)	
J310ZL1	TO-92	2000 Units / Tape & Ammo Box
J310ZL1G	TO-92 (Pb-Free)	

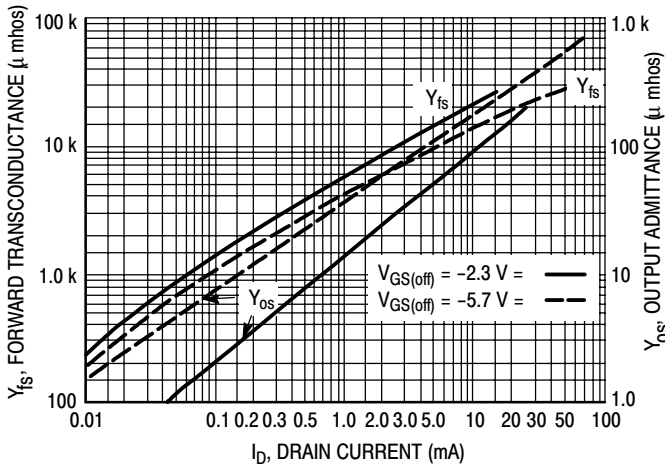
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



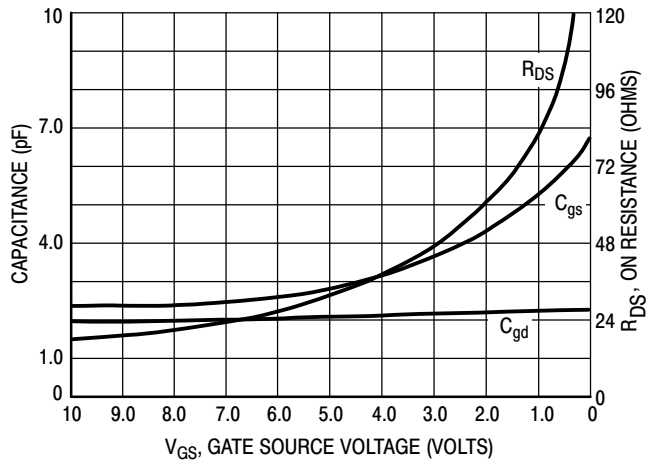
**Figure 1. Drain Current and Transfer Characteristics versus Gate-Source Voltage**



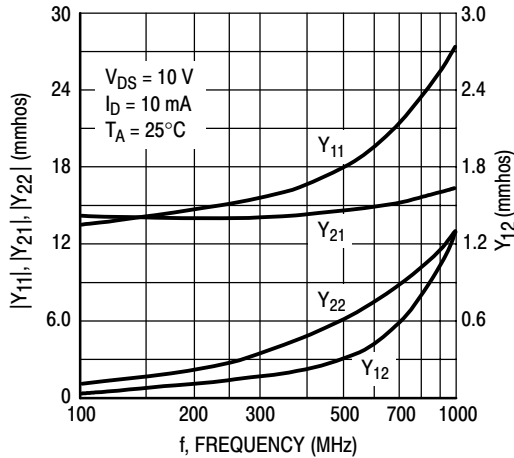
**Figure 2. Forward Transconductance versus Gate-Source Voltage**



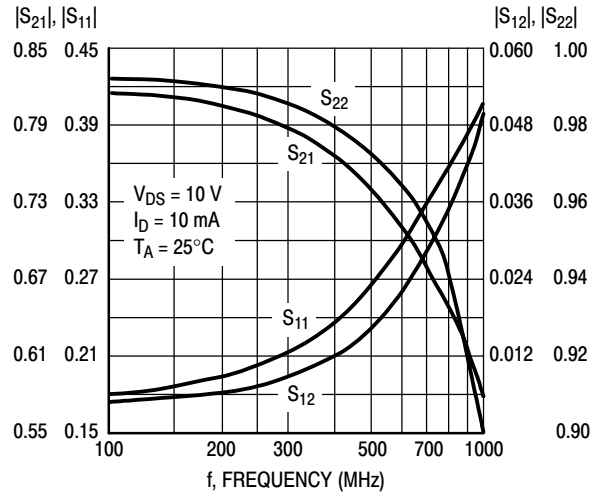
**Figure 3. Common-Source Output Admittance and Forward Transconductance versus Drain Current**



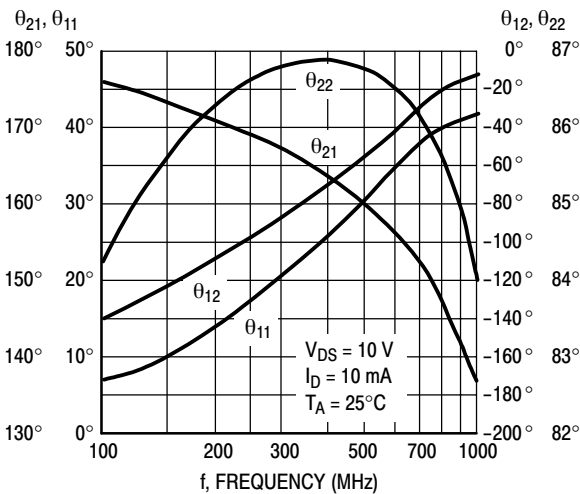
**Figure 4. On Resistance and Junction Capacitance versus Gate-Source Voltage**



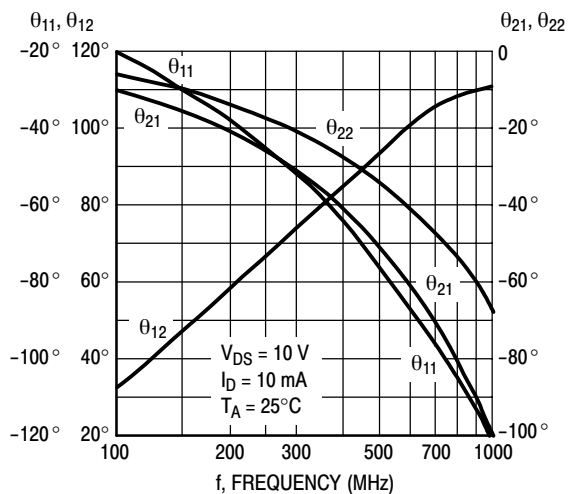
**Figure 5. Common-Gate Y Parameter Magnitude versus Frequency**



**Figure 6. Common-Gate S Parameter Magnitude versus Frequency**



**Figure 7. Common-Gate Y Parameter Phase-Angle versus Frequency**

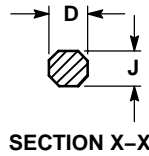
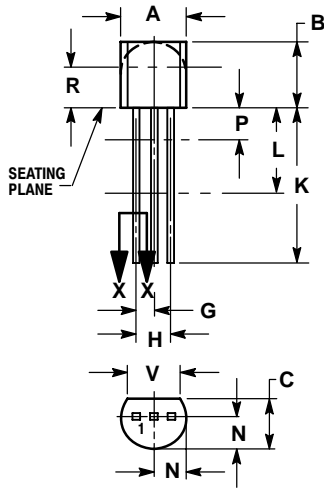


**Figure 8. S Parameter Phase-Angle versus Frequency**

# J309, J310

## PACKAGE DIMENSIONS

### TO-92 (TO-226) CASE 29-11 ISSUE AL



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---

**STYLE 5:**

1. DRAIN
2. SOURCE
3. GATE

**ON Semiconductor** and **ON** are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

### PUBLICATION ORDERING INFORMATION

**LITERATURE FULFILLMENT:**

Literature Distribution Center for ON Semiconductor  
P.O. Box 61312, Phoenix, Arizona 85082-1312 USA  
**Phone:** 480-829-7710 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 480-829-7709 or 800-344-3867 Toll Free USA/Canada  
**Email:** orderlit@onsemi.com

**N. American Technical Support:** 800-282-9855 Toll Free USA/Canada

**Japan:** ON Semiconductor, Japan Customer Focus Center  
2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051  
**Phone:** 81-3-5773-3850

**ON Semiconductor Website:** <http://onsemi.com>

**Order Literature:** <http://www.onsemi.com/litorder>

For additional information, please contact your local Sales Representative.

# Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[ON Semiconductor:](#)

[J310G](#) [J310ZL1](#)